

ABSTRACT OF THE DISCLOSURE

The present invention relates to the field of fabricating elements on a substrate. In one embodiment, the invention is an apparatus. The apparatus includes a strap having embedded therein an integrated circuit, the integrated circuit having a conductive pad. The apparatus also includes a conductive medium attached to the conductive pad of the integrated circuit.

In an alternate embodiment, the invention is a method. The method includes attaching a conductive medium to a strap having embedded therein an integrated circuit such that the conductive medium is connected electrically to the integrated circuit. The method also includes attaching a large-scale component to the conductive medium such that the large-scale component is electrically connected to the conductive medium.

In another alternate embodiment, the invention is an apparatus. The apparatus includes an integrated circuit embedded within a substrate. The apparatus also includes a thin-film dielectric layer formed over a portion of the integrated circuit and a portion of the substrate. The apparatus further includes a conductive medium formed over a portion of the thin-film dielectric layer, the conductive medium having direct electrical connection with the integrated circuit.

In yet another alternate embodiment, the invention is a method. The method includes forming a thin-film insulator on a portion of an integrated circuit and a portion of a substrate, the integrated circuit embedded within the substrate. The method also includes attaching a conductive medium to the thin-

film insulator and to the integrated circuit, the conductive medium electrically connected to the integrated circuit.